

# BASIC BLADE & BEAM HEADER & SOCKET

(0.80 mm) .0315" PITCH • BTE/BSE SERIES



**BTE**  
Mates:  
BSE

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BTE

## SPECIFICATIONS

**Insulator Material:**  
Liquid Crystal Polymer  
**Contact Material:**  
Phosphor Bronze  
**Plating:**  
Au or Sn over 50 μ" (1.27 μm) Ni  
**Current Rating:**  
2 A per pin  
(2 pins powered)  
**Operating Temp Range:**  
-55 °C to +125 °C  
**Voltage Rating:**  
225 VAC with 5 mm Stack Height  
**Max Cycles:**  
100

## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Coplanarity:**  
(0.10 mm) .004" max (020-080)  
(0.15 mm) .006" max (100-120)\*  
\*(.004" stencil solution may be available; contact IPG@samtec.com)  
**Board Stacking:**  
For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

## ALSO AVAILABLE

MOQ Required

30 μ" (0.76 μm) Gold  
Edge Mount Capability  
Friction Lock option  
11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)



**Note:**  
Some lengths, styles and options are non-standard, non-returnable.

BTE	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
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-020, -040, -060,  
-080, -100, -120

Specify  
LEAD  
STYLE  
from  
chart

**-F**  
= Gold Flash on contact,  
Matte Tin on tail

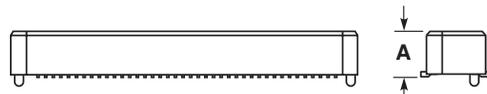
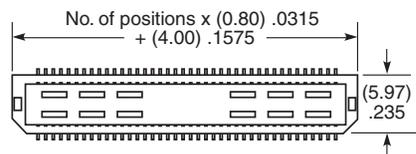
**-L**  
= 10 μ" (0.25 μm)  
Gold on contact,  
Matte Tin on tail

**-C\***  
= Electro-Polished Selective  
50 μ" (1.27 μm) min  
Au over 150 μ" (3.81 μm)  
Ni on Signal Pins in contact  
area, Matte Tin over  
50 μ" (1.27 μm) min  
Ni on all solder tails  
(\*-C Plating passes  
10 year MFG testing)

**-K**  
= (7.00 mm)  
.275" DIA  
Polyimide Film  
Pick & Place Pad

**-TR**  
= Tape & Reel  
(80 positions  
maximum)

**-FR**  
= Full Reel  
Tape & Reel  
(must order  
maximum  
quantity per  
reel; contact  
Samtec for  
quantity breaks)  
(80 positions  
maximum)



LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

## MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"
-02	(8.00 mm) .315"

\*Processing conditions will affect mated height.

BSE	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
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-020, -040, -060,  
-080, -100, -120

**-F**  
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Matte Tin on tail

**-L**  
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Gold on contact,  
Matte Tin on tail

**-C\***  
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